

From / to	molding temperature		PP	PE	PS (GPPS)	HIPS	ABS	AS	POM	PA6/66/12	PBT	PC	PC (tran)	PC-ABS
PP	180~280°C	Purge material	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
PE	180~260°C	Purge material	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
PS (GPPS)	170~260°C	Purge material	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
HIPS	170~260°C	Purge material	GWP	GWP	GWP	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
ABS	180~270°C	Purge material	GWP	GWP	GWP	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
AS	180~270°C	Purge material	GWP	GWP	GWP	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
POM ¹	180~220°C	Purge material	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP	GWP
		Temperature	185°C-200°C	185°C-200°C	185°C-200°C	185°C-200°C	185°C-200°C	185°C-200°C	185°C-200°C	185°C-200°C	185°C-200°C	185°C-200°C	185°C-200°C	185°C-200°C
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
		Purge material	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS
		Temperature	200°C up	200°C up	200°C up	200°C up	200°C up	200°C up	200°C up	200°C up	200°C up	200°C up	200°C up	200°C up
		discharge			Low MFR GPPS			Low MFR AS					Low MFR PC	Low MFR PC
PA6/PA66/ PA12	230~300°C	Purge material	GWP	GWP	GWP	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
PBT	230~270°C	Purge material	GWP	GWP	GWP	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
PC	250~320°C	Purge material	GWP	GWP	GWP	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
PC (trans)	250~320°C	Purge material	GWP	GWP	GWP	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS
		discharge			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	
PC-ABS	250~320°C	Purge material	GWP	GWP	GWP	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS	GWS
		Temperature			Low MFR GPPS			Low MFR AS				Low MFR PC	Low MFR PC	

¹ In the case of TENAC™ from ASAHI KASEI, the phenomenon of popping may occur. It can be solved if PP is poured before purging with ecomaru. Please contact us for detail information.

For purging pellet, it is important to balance both cleaning ability and discharge ability.

Purging	Discharging	Remark
<p>This is the recommended standard grades. Please use it within the temperature range of ecomaru. (GWS 200°C~320°C、 GWP 180°C~280°C) If there is a temperature difference between the pre-resin and next resin, clean the pre-resin and discharg, then change the temperature. If you have any questions, please contact us in advance. ecomaru cleaning is recommended to use both Auto purge (up to 3 shots) and Short purge. Shot purge is a method to reduce thr amount and injection with faster speed. By changing the flow of resin, carbides remaining in the nozzle and dead space are discharged. Thia method is also effective for discharge. Recommended conditions: optimal temperature 240°C±20°C appropriate injection pressure 60Mpa</p>	<p>ecomaru does not have another grade for discharge. Remaining GW or incomplete discharge of ecomaru after purging may cause contamination of mold products. Please discharge ecomaru with next resin or following method. ※ In this case, please pay attention to MFR of the next resin. ecomaru may not discharged if the next resin is high flow. ※ Please use PP resin (recommend MFR 5~10) , if you can no discharge with next resin. ※ If the next resin does not discharge enough with GWS, please try GWP. ※ If different resins are used for discharging transparent resin,it may cause defects such as cloudiness. Therefore, for transparent resin, use rhe same resin with low MFR.</p>	<p>※ While purging ecomaru at the first time, carbides or color residue that have not been removed may be discharged. This shows the cleaning ability of ecomaru. ※ In this case, we recommend to purge by adding the amount until the purgie waste color becomes the primary color. ※ The black dot defect rate may increase only on the day of purging, This indicates the cleaning ability of ecomaru and will decrease from the next day onwards.</p>